National Semiconductor

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MM54HC174/MM74HC174
Hex D Flip-Flops with Clear

General Description

These edge triggered flip-flops utilize advanced silicon-gate CMOS technology to implement D-type flip-flops. They possess high noise immunity, low power, and speeds comparable to low power Schottky TTL circuits. This device contains 6 master-slave flip-flops with a common clock and common clear. Data on the D input having the specified setup and hold times is transferred to the Q output on the low to high transition of the CLOCK input. The CLEAR input when low, sets all outputs to a low state.

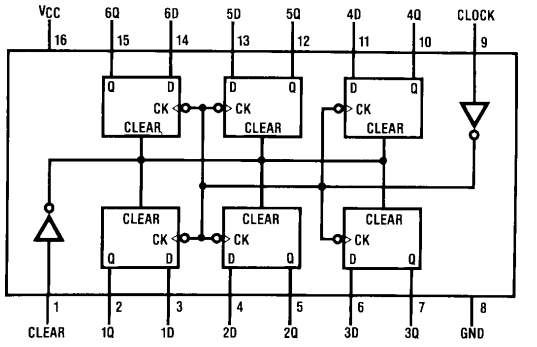
Each output can drive 10 low power Schottky TTL equivalent loads. The MM54HC174/MM74HC174 is functionally as well as pin compatible to the 54LS174/74LS174. All inputs are protected from damage due to static discharge by diodes to V_{CC} and ground.

Features

- Typical propagation delay: 16 ns
- Wide operating voltage range: 2–6V
- Low input current: 1 μA maximum
- Low quiescent current: 80 μA (74HC Series)
- Output drive: 10 LSTTL loads

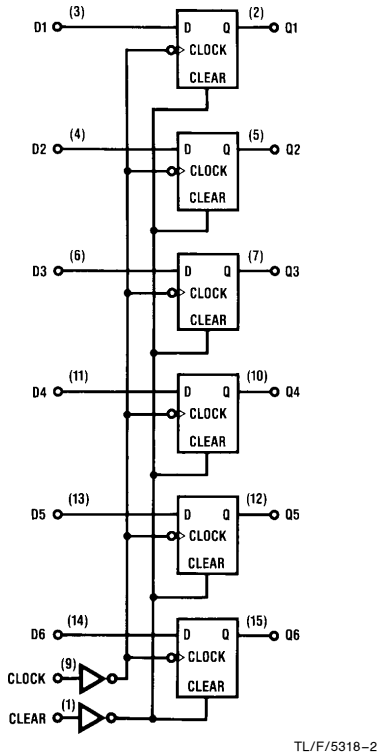
Connection and Logic Diagrams

Dual-In-Line Package



TL/F/5318–1

Order Number MM54HC174 or MM74HC174



TL/F/5318–2

Truth Table

(Each Flip-Flop)

Inputs			Outputs
Clear	**Clock**	**D**	**Q**
L	X	X	L
H	↑	H	H
H	↑	L	L
H	L	X	Q_0

H = High level (steady state)
L = Low level (steady state)
X = Don't Care
↑ = Transition from low to high level
Q_0 = The level of Q before the indicated steady state input conditions were established.

RRD-B30M105/Printed in U. S. A.

Absolute Maximum Ratings (Notes 1 & 2)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Supply Voltage (V_{CC})	−0.5 to +7.0V
DC Input Voltage (V_{IN})	−1.5 to V_{CC} +1.5V
DC Output Voltage (V_{OUT})	−0.5 to V_{CC} +0.5V
Clamp Diode Current (I_{IK}, I_{OK})	±20 mA
DC Output Current, per pin (I_{OUT})	±25 mA
DC V_{CC} or GND Current, per pin (I_{CC})	±50 mA
Storage Temperature Range (T_{STG})	−65°C to +150°C
Power Dissipation (P_D) (Note 3)	600 mW
S.O. Package only	500 mW
Lead Temperature (T_L) (Soldering 10 seconds)	260°C

Operating Conditions

		Min	Max	Units
Supply Voltage (V_{CC})		2	6	V
DC Input or Output Voltage (V_{IN}, V_{OUT})		0	V_{CC}	V
Operating Temp. Range (T_A)				
MM74HC		−40	+85	°C
MM54HC		−55	+125	°C
Input Rise or Fall Times (t_r, t_f)	V_{CC} = 2.0V		1000	ns
	V_{CC} = 4.5V		500	ns
	V_{CC} = 6.0V		400	ns

DC Electrical Characteristics (Note 4)

Symbol	Parameter	Conditions	V_{CC}	T_A = 25°C	74HC T_A = −40 to 85°C	54HC T_A = −55 to 125°C	Units
				Typ	Guaranteed Limits		
V_{IH}	Minimum High Level Input Voltage		2.0V		1.5	1.5	1.5	V
			4.5V		3.15	3.15	3.15	V
			6.0V		4.2	4.2	4.2	V
V_{IL}	Maximum Low Level Input Voltage**		2.0V		0.5	0.5	0.5	V
			4.5V		1.35	1.35	1.35	V
			6.0V		1.8	1.8	1.8	V
V_{OH}	Minimum High Level Output Voltage	V_{IN} = V_{IH} or V_{IL} $\|I_{OUT}\| \leq 20\ \mu A$	2.0V	2.0	1.9	1.9	1.9	V
			4.5V	4.5	4.4	4.4	4.4	V
			6.0V	6.0	5.9	5.9	5.9	V
		V_{IN} = V_{IH} or V_{IL} $\|I_{OUT}\| \leq 4.0$ mA	4.5V	4.2	3.98	3.84	3.7	V
		$\|I_{OUT}\| \leq 5.2$ mA	6.0V	5.7	5.48	5.34	5.2	V
V_{OL}	Maximum Low Level Output Voltage	V_{IN} = V_{IH} or V_{IL} $\|I_{OUT}\| \leq 20\ \mu A$	2.0V	0	0.1	0.1	0.1	V
			4.5V	0	0.1	0.1	0.1	V
			6.0V	0	0.1	0.1	0.1	V
		V_{IN} = V_{IH} or V_{IL} $\|I_{OUT}\| \leq 4.0$ mA	4.5V	0.2	0.26	0.33	0.4	V
		$\|I_{OUT}\| \leq 5.2$ mA	6.0V	0.2	0.26	0.33	0.4	V
I_{IN}	Maximum Input Current	V_{IN} = V_{CC} or GND	6.0V		±0.1	±1.0	±1.0	μA
I_{CC}	Maximum Quiescent Supply Current	V_{IN} = V_{CC} or GND I_{OUT} = 0 μA	6.0V		8.0	80	160	μA

Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 3: Power Dissipation temperature derating — plastic "N" package: −12 mW/°C from 65°C to 85°C; ceramic "J" package: −12 mW/°C from 100°C to 125°C.

Note 4: For a power supply of 5V ±10% the worst case output voltages (V_{OH}, and V_{OL}) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case V_{IH} and V_{IL} occur at V_{CC} = 5.5V and 4.5V respectively. (The V_{IH} value at 5.5V is 3.85V.) The worst case leakage current (I_{IN}, I_{CC}, and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0V values should be used.

**V_{IL} limits are currently tested at 20% of V_{CC}. The above V_{IL} specification (30% of V_{CC}) will be implemented no later than Q1, CY'89.

AC Electrical Characteristics $V_{CC} = 5V$, $T_A = 25°C$, $C_L = 15$ pF, $t_r = t_f = 6$ ns

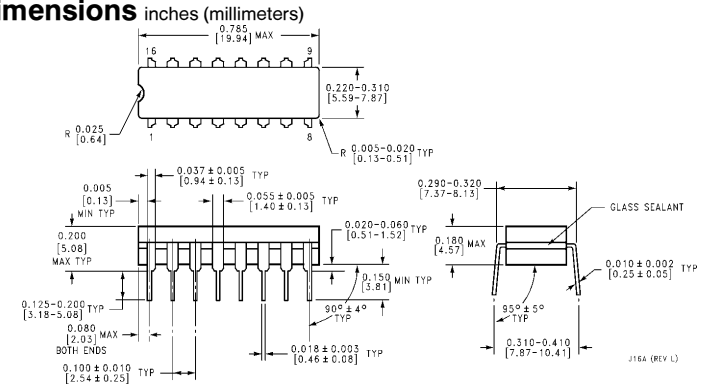
Symbol	Parameter	Conditions	Typ	Guaranteed Limit	Units
f_{MAX}	Maximum Operating Frequency		50	30	MHz
t_{PHL}, t_{PLH}	Maximum Propagation Delay, Clock or Clear to Output		16	30	ns
t_{REM}	Minimum Removal Time, Clear to Clock		−2	5	ns
t_S	Minimum Setup Time Data to Clock		10	20	ns
t_H	Minimum Hold Time Clock to Data		0	5	ns
t_W	Minimum Pulse Width Clock or Clear		10	16	ns

AC Electrical Characteristics $C_L = 50$ pF, $t_r = t_f = 6$ ns (unless otherwise specified)

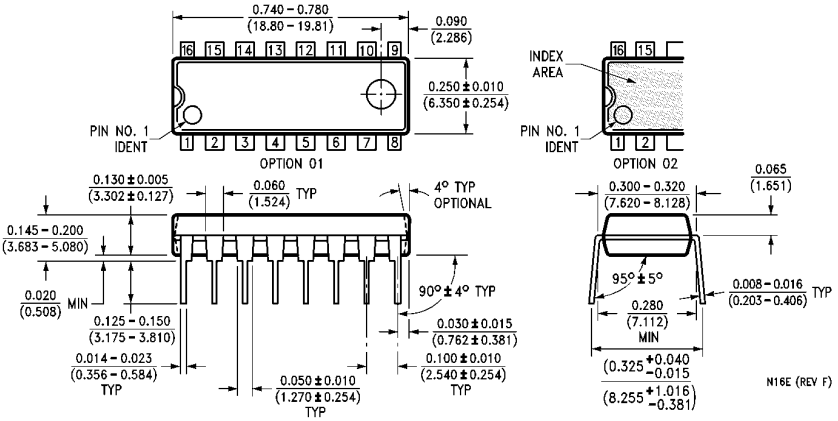
Symbol	Parameter	Conditions	V_{CC}	$T_A = 25°C$	74HC $T_A = -40$ to $85°C$	54HC $T_A = -55$ to $125°C$	Units
				Typ	Guaranteed Limits		
f_{MAX}	Maximum Operating Frequency		2.0V 4.5V 6.0V	 	5 27 31	4 21 24	3 18 20	MHz MHz MHz
t_{PHL}, t_{PLH}	Maximum Propagation Delay Clock or Clear to Output		2.0V 4.5V 6.0V	55 18 16	165 33 28	206 41 35	248 49 42	ns ns ns
t_{REM}	Minimum Removal Time Clear to Clock		2.0V 4.5V 6.0V	1 1 1	5 5 5	5 5 5	5 5 5	ns ns ns
t_S	Minimum Setup Time Data to Clock		2.0V 4.5V 6.0V	42 12 10	100 20 17	125 25 21	150 30 25	ns ns ns
t_H	Minimum Hold Time Clock to Data		2.0V 4.5V 6.0V	1 1 1	5 5 5	5 5 5	5 5 5	ns ns ns
t_W	Minimum Pulse Width Clock or Clear		2.0V 4.5V 6.0V	35 10 8	80 16 14	106 20 18	120 24 20	ns ns ns
t_{TLH}, t_{THL}	Maximum Output Rise and Fall Time		2.0V 4.5V 6.0V	30 8 7	75 15 13	95 19 16	110 22 19	ns ns ns
t_r, t_f	Maximum Input Rise and Fall Time		2.0V 4.5V 6.0V	 	1000 500 400	1000 500 400	1000 500 400	ns ns ns
C_{PD}	Power Dissipation Capacitance (Note 5)	(per package)		136				pF
C_{IN}	Maximum Input Capacitance			5	10	10	10	pF

Note 5: C_{PD} determines the no load dynamic power consumption, $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD} V_{CC} f + I_{CC}$.

Physical Dimensions inches (millimeters)



Dual-In Line Package (J)
Order Number MM54HC174J or MM74HC174J
See NS Package J16A



Dual-In Line Package (N)
Order Number MM74HC174N
See NS Package N16E

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